

M14C16 Die Description

PRODUCT M14C16

WAFER SIZE 152 mm (6 inches)
■ DIE IDENTIFICATION M14C16KA_R
■ DIE SIZE (X x Y) 1390 x 2375 μm
■ SCRIBE LINE 101.8 x 102.4 μm
■ PAD OPENING 100 x 100 μm

DIE LAYOUT

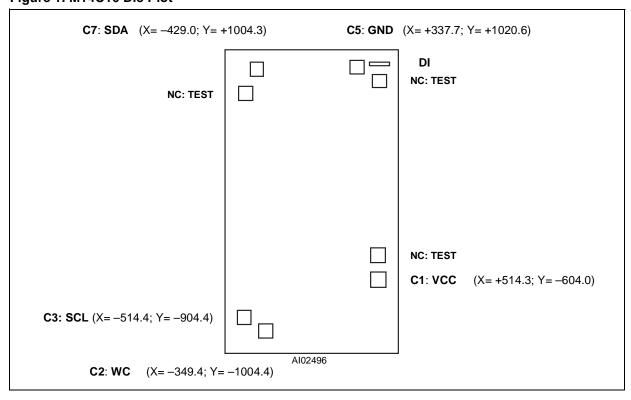
■ DI Die Identification (at the position shown in Figure 1)

■ C1, C2, C3, C5, C7 Pad contacts to the ISO pins (at the positions shown in Figure 1)

■ C4, C6, C8
■ NC
These ISO pins do not appear on the M14C16 die
■ NC
This pad, shown in Figure 1, is Not Connected

Pad locations are measured relative to the die centre (where X and Y are respectively the horizontal and vertical axis, measured in μ m).

Figure 1. M14C16 Die Plot



DD.M14C16/9811V1.1 1/2

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47/